

SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
260 °C/10 seconds at terminals

Mechanical Data

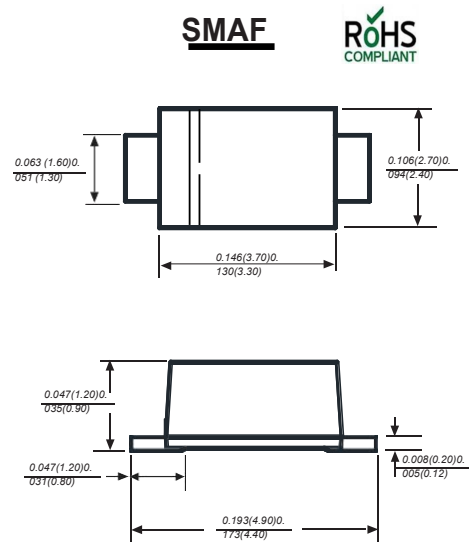
Case : JEDEC SMAF molded plastic body

Terminals : Solderable per MIL-STD-750, Method 2026

Polarity : Color band denotes cathode end

Mounting Position : Any

Weight : 0.0018 ounce, 0.064 grams



Dimensions in inches and (millimeters)

Maximum Ratings And Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

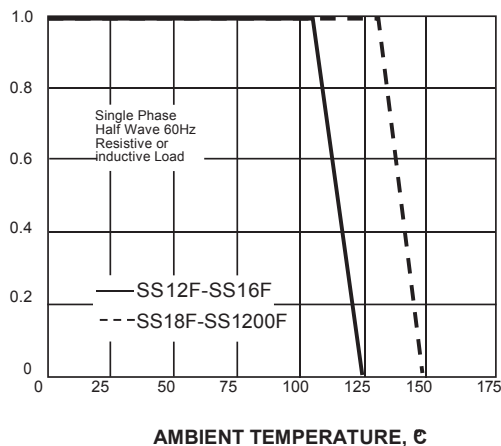
Parameter	SYMBOLS	SS12F RCD SS12F	SS13F RCD SS13F	SS14F RCD SS14F	SS15F RCD SS15F	SS16F RCD SS16F	SS18F RCD SS18F	SS110F RCD SS110F	SS1150F RCD SS1150F	SS1200F RCD SS1200F	UNITS
Marking Code											
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current at TL(see fig.1)	I _{AV}	1.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	I _{FSM}	30									A
Maximum instantaneous forward voltage at 1.0A	V _F	0.55			0.70		0.85			0.95	V
Maximum DCreverse current T _A =25℃T _A at rated DCblocking voltage =125℃	I _R	0.5						0.22		mA	
		10.0				5.0		.0			
Typical junction capacitance (NOTE 1)	C _J	110			90						pF
Typical thermal resistance (NOTE 2)	R _{θJA}	88.0									℃/W
Operating junction temperature range	T _J	-50 to +125					-50 to +150				℃
Storage temperature range	T _{STG}	-50 to +150									℃

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas

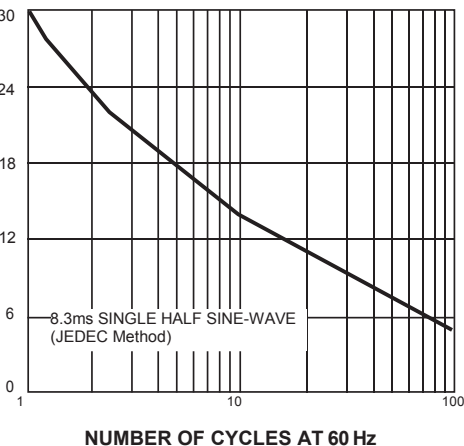
AVERAGE FORWARD RECTIFIED CURRENT,
AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



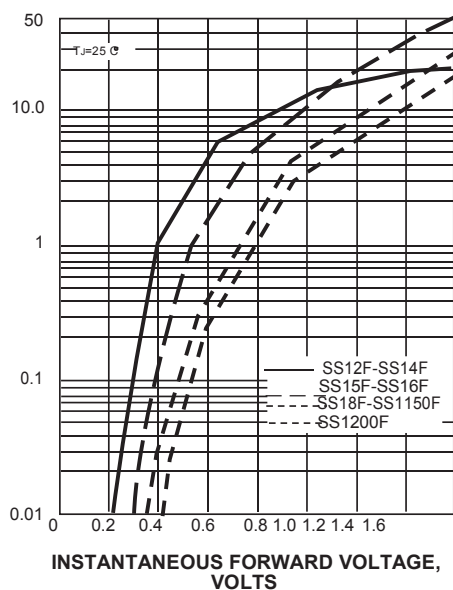
PEAK FORWARD SURGE CURRENT,
AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



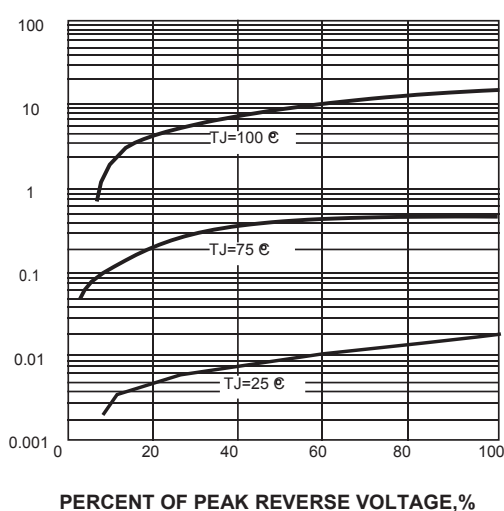
INSTANTANEOUS FORWARD
CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



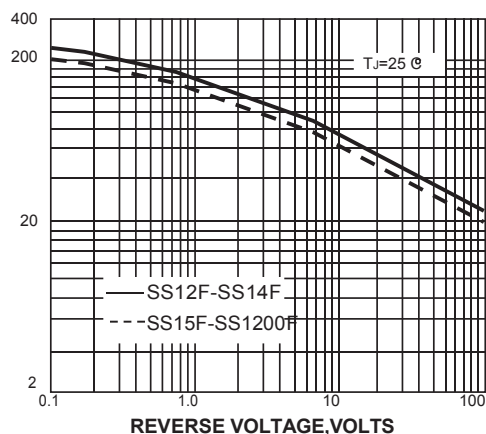
INSTANTANEOUS REVERSE CURRENT,
MILLIAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



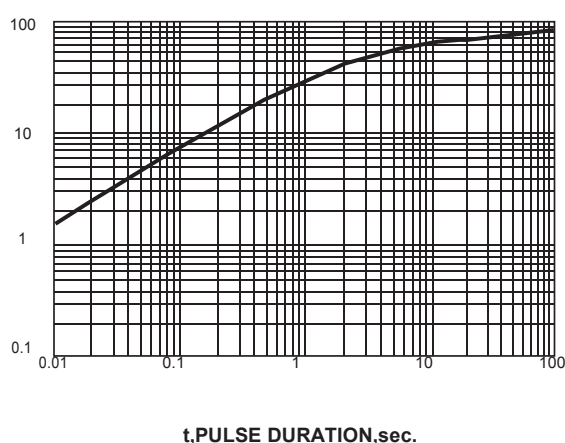
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE



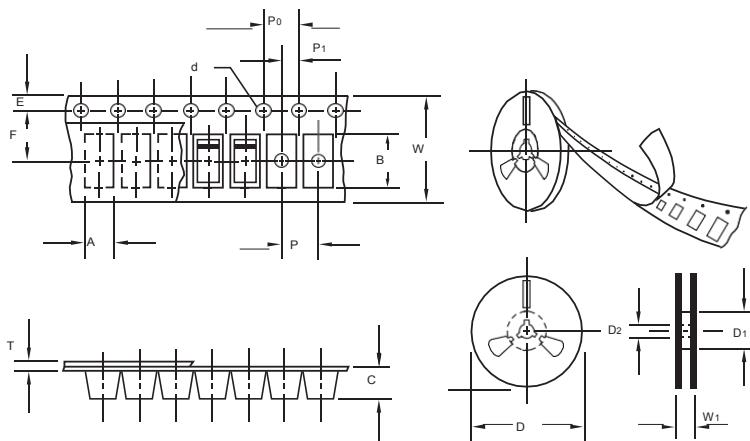
TRANSIENT THERMAL IMPEDANCE,
C/W

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



The curve above is for reference only.

Packing information



unit:mm

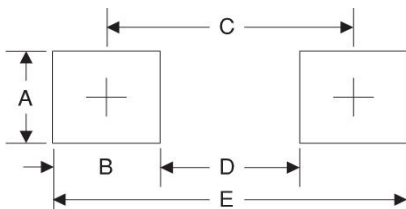
Item	Symbol	Tolerance	SMAF
Carrier width	A	0.1	2.80
Carrier length	B	0.1	4.75
Carrier depth	C	0.1	1.42
Sprocket hole	d	0.05	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	54.40
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.05
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	8.00
Reel width	W1	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA. (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMAF	7"	3,000	4.0	6,000	210*208*203	178	400*265*400	120,000	10.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.8	0.071
B	1.6	0.063
C	3.8	0.150
D	2.2	0.087
E	5.4	0.213